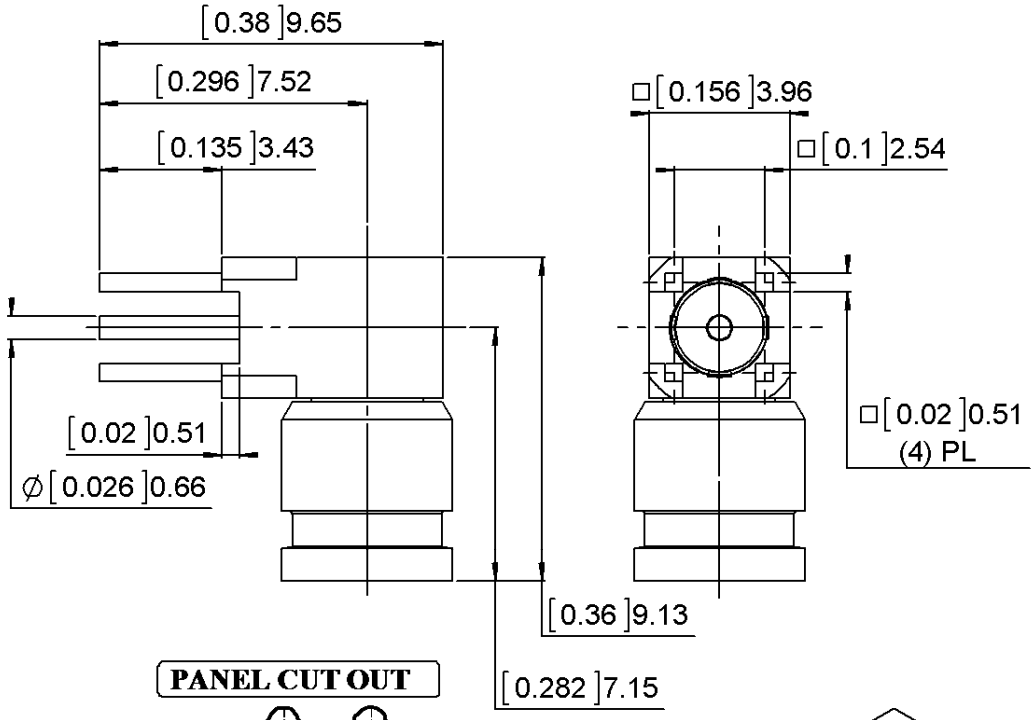
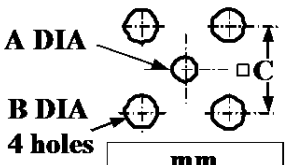
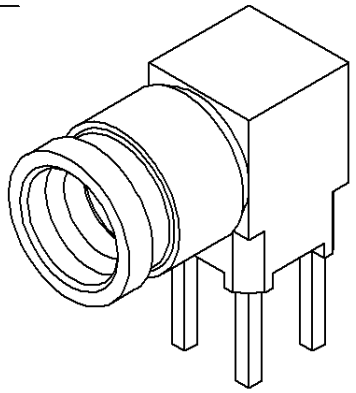
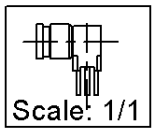


PANEL CUT OUT

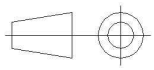


	mm	
	Maxi	mini
A	.965	.914
B	1.016	.965
C	2.591	2.489





All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS.**	**GOLD 1.3 OVER NICKEL 2**
Center contact	**BERYLLIUM COPPER**	**GOLD 1.27 OVER NICKEL 1.27**
Outer contact		
Insulator	**PEEK**	
Gasket		
Others parts	**BRASS.**	**GOLD 1.3 OVER NICKEL 2**
-	-	-
-	-	-

PACKAGING

Standard	Unit	Other
100	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-12**	GHz
VSWR	**NA**	**+**	**0.0000**	x F(GHz) Maxi
Insertion loss			**NA**	√F(GHz) dB Maxi
RF leakage		- (	**NA**	- F(GHz)) dB Maxi
Voltage rating			**335**	Veff Maxi
Dielectric withstanding voltage			**500**	Veff mini
Insulation resistance			**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**6.7**	N mini
Axial force – Opposite end	**6.7**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**500**	Cycles mini
Weight	**1.1100**	g

ENVIRONMENTAL

Operating temperature	**-40/+250**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

***Optional potting procedure recommended for extreme environmental conditions at 20 G-rms acceleration and operating temperature > 165°C:**

Adhesive potting material is recommended after soldering to the PCB and mating to plug.
Full encapsulation of the connecter provides maximum bonding capability of the body, legs, and center contact to the PCB.